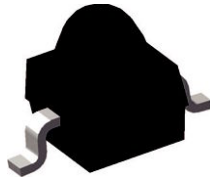


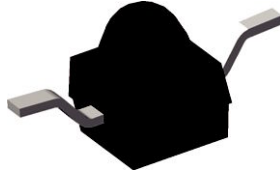


Silicon PIN Photodiode



21568-1

VEMD2020X01



VEMD2000X01

DESCRIPTION

VEMD2000X01 and VEMD2020X01 are high speed and high sensitive PIN photodiodes in a miniature surface mount package (SMD) with dome lens and daylight blocking filter. Filter is matched with IR emitters operating at wavelength of 830 nm to 950 nm. The photo sensitive area of the chip is 0.23 mm².

FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- High radiant sensitivity
- Daylight blocking filter matched with 830 nm to 950 nm IR emitters
- Fast response times
- Angle of half sensitivity: $\phi = \pm 15^\circ$
- Package matched with IR emitter series VSMB2000X01
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



Note

** Please see document "Vishay Material Category Policy": www.vishay.com/doc?99902

APPLICATIONS

- High speed photo detector
- Infrared remote control
- Infrared data transmission
- Photo interrupters
- Shaft encoders

PRODUCT SUMMARY			
COMPONENT	I _{ra} (μA)	φ (deg)	λ _{0.5} (nm)
VEMD2000X01	12	± 15	750 to 1050
VEMD2020X01	12	± 15	750 to 1050

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VEMD2000X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VEMD2020X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	60	V
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	- 40 to + 100	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	Acc. reflow solder profile fig. 7	T _{sd}	260	°C
Thermal resistance junction/ambient	Acc. J-STD-051	R _{thJA}	250	K/W



BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F		1		V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	32			V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}		1	10	nA
Diode capacitance	V _R = 0 V, f = 1 MHz, E = 0	C _D		4		pF
	V _R = 5 V, f = 1 MHz, E = 0	C _D		1.3		pF
Open circuit voltage	E _e = 1 mW/cm ² , λ = 950 nm	V _o		350		mV
Temperature coefficient of V _o	E _e = 1 mW/cm ² , λ = 950 nm	TK _{V_o}		- 2.6		mV/K
Short circuit current	E _e = 1 mW/cm ² , λ = 950 nm	I _k		11		μA
Temperature coefficient of I _k	E _e = 1 mW/cm ² , λ = 950 nm	TK _{I_k}		0.1		%/K
Reverse light current	E _e = 1 mW/cm ² , λ = 950 nm, V _R = 5 V	I _{ra}	8.5	12	17	μA
Angle of half sensitivity		φ		± 15		deg
Wavelength of peak sensitivity		λ _p		940		nm
Range of spectral bandwidth		λ _{0.5}		750 to 1050		nm
Rise time	V _R = 10 V, R _L = 1 kΩ, λ = 820 nm	t _r		100		ns
Fall time	V _R = 10 V, R _L = 1 kΩ, λ = 820 nm	t _f		100		ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)



Fig. 1 - Reverse Dark Current vs. Ambient Temperature

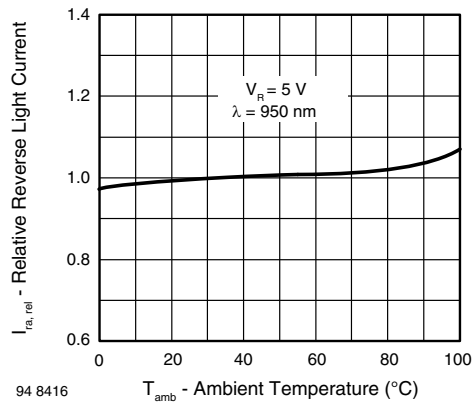


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

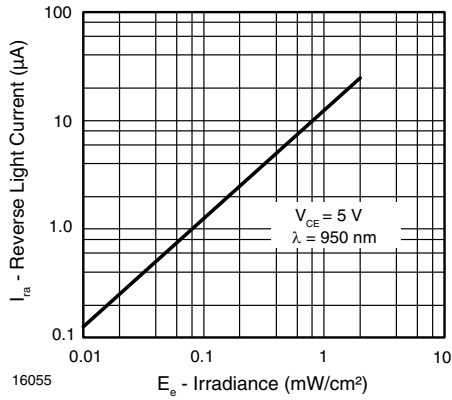


Fig. 3 - Reverse Light Current vs. Irradiance

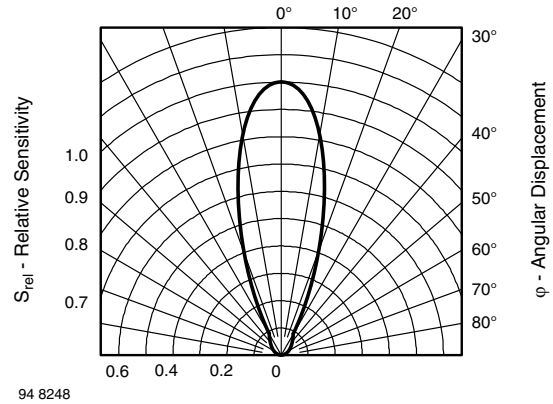


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

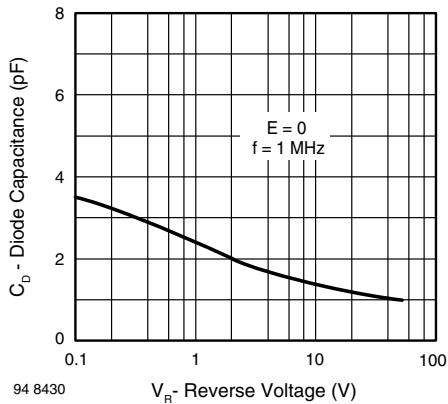


Fig. 4 - Diode Capacitance vs. Reverse Voltage

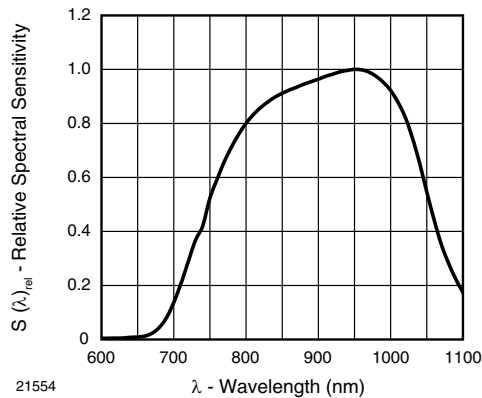


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

REFLOW SOLDER PROFILE

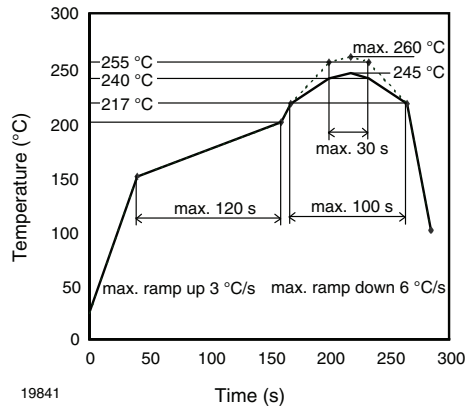


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

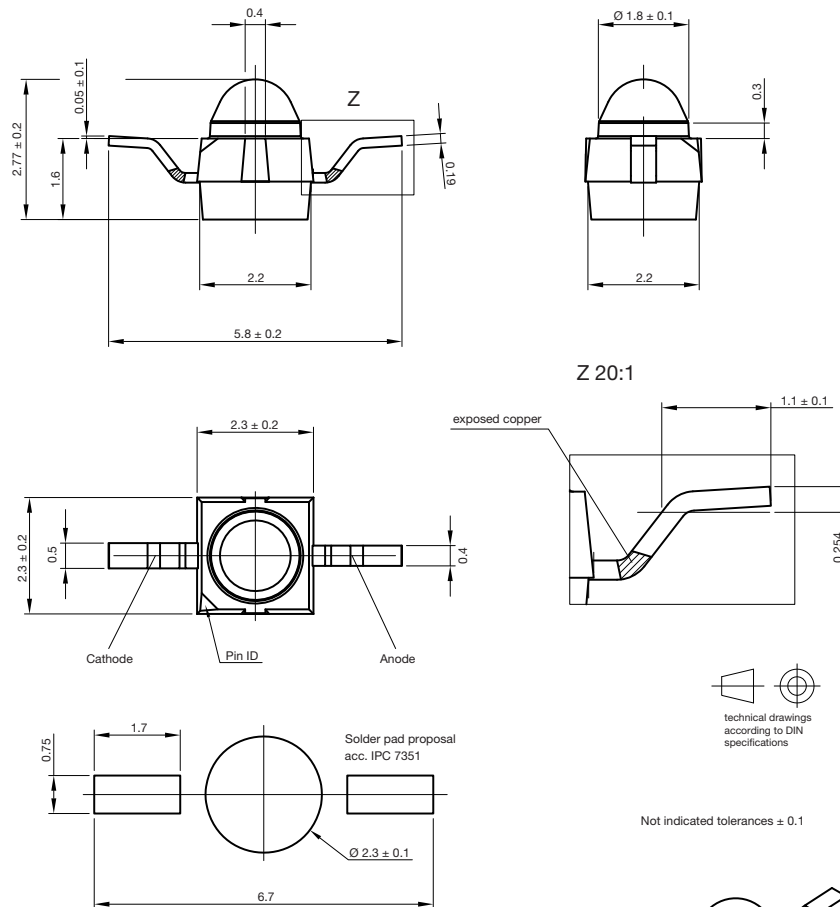
Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

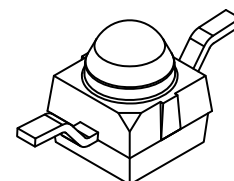
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ }^{\circ}\text{C}$ (+ 5 $^{\circ}\text{C}$), RH < 5 %.

PACKAGE DIMENSIONS in millimeters: VEMD2000

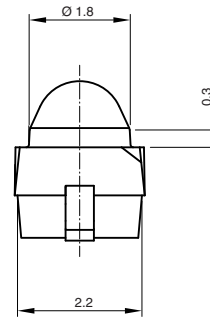
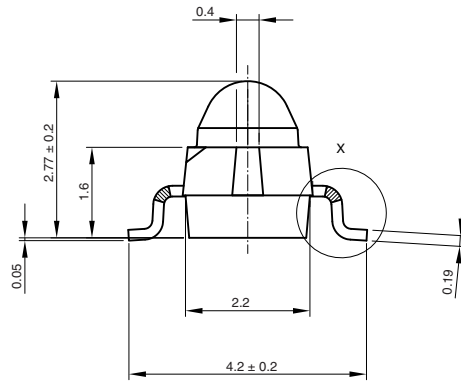


Drawing-No.: 6.544-5391.02-4
Issue: 2; 18.03.10
21517

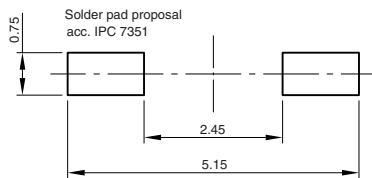
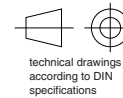
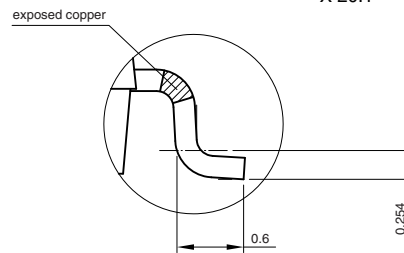




PACKAGE DIMENSIONS in millimeters: VEMD2020

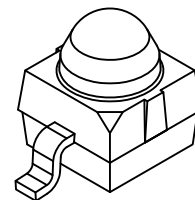


X 20:1



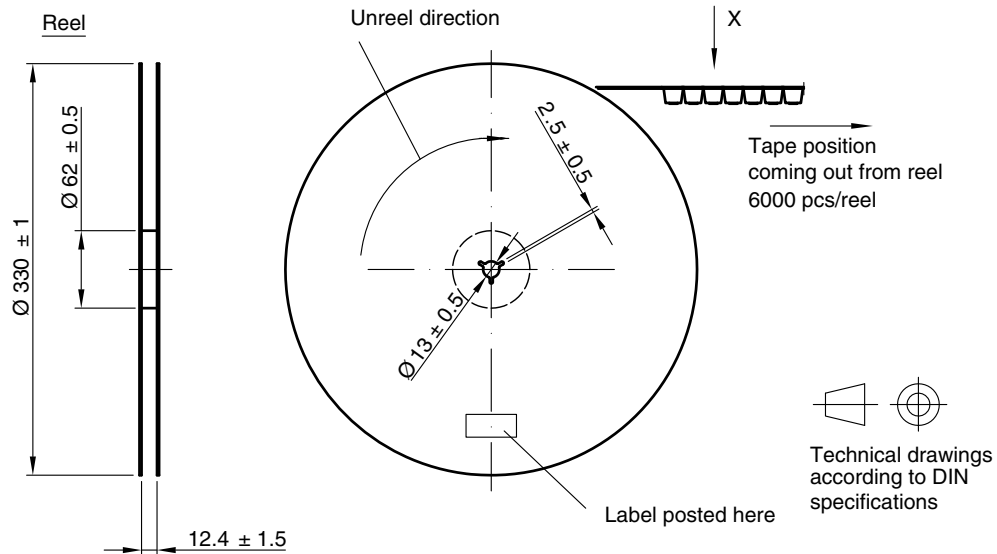
Not indicated tolerances ± 0.1

Drawing-No.: 6.544-5383.02-4
 Issue: 4; 18.03.10
 21488

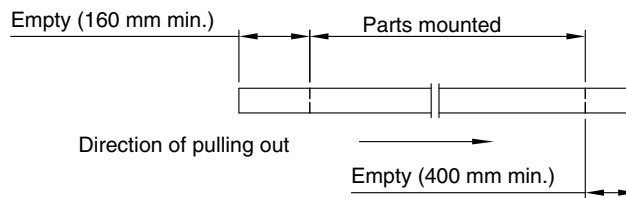




TAPING AND REEL DIMENSIONS in millimeters: **VEMD2000**

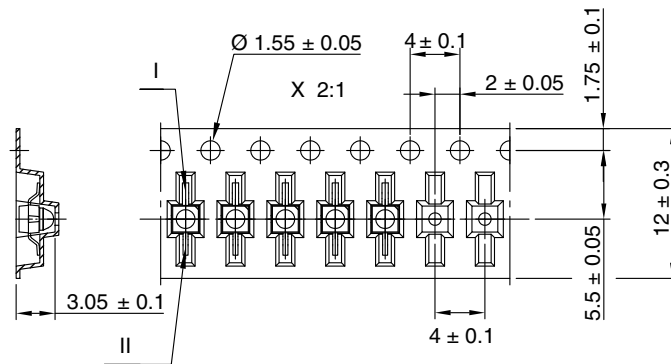


Leader and trailer tape:



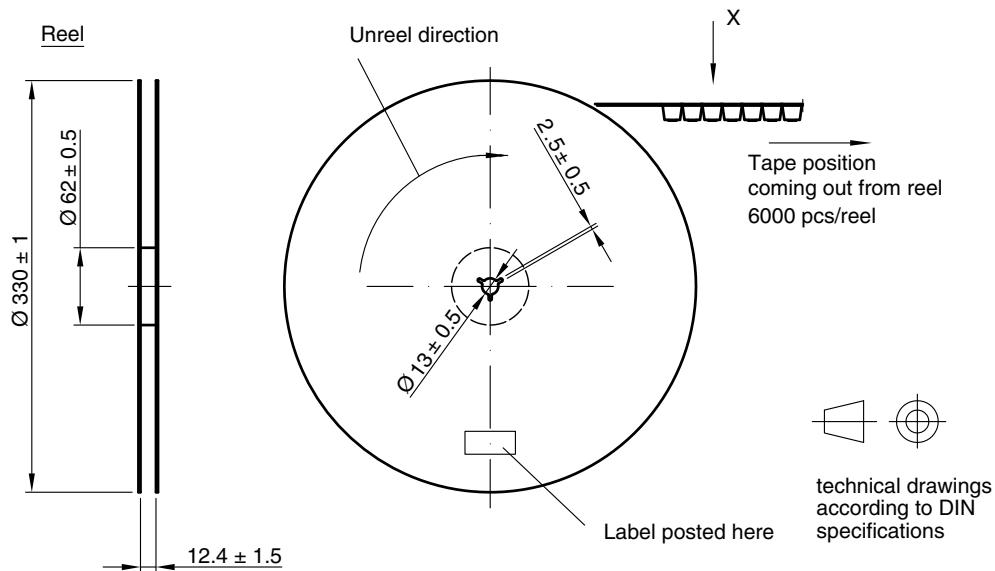
Terminal position in tape

Device	Lead I	Lead II
VEMT2000	Collector	Emitter
VEMT2500		
VEMD2000	Cathode	Anode
VEMD2500		
VSMB2000		
VSMG2000		
VSMY2850RG	Anode	Cathode



Drawing-No.: 9.800-5100.01-4
 Issue: 2; 18.03.10
 21572

TAPING AND REEL DIMENSIONS in millimeters: VEMD2020



Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II
VEMT2020	Collector	Emitter
VEMT2520		
VSMB2020	Cathode	Anode
VSMG2020		
VEMD2020		
VEMD2520	Anode	Cathode
VSMY2850G		



Drawing-No.: 9.800-5091.01-4

Issue: 3; 18.03.10

21571



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